Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	9 X 9 X 0.75 (4.5 EP)
Lead Count	64
Terminal Finish	100 Sn
MS Number	MS010617C

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	7.63E-02	86.20	862000	33.46	334609
Thermosets	Epoxy resin	Proprietary	5.31E-03	6.00	60000	2.33	23291
Thermosets	Phenol Resin	Proprietary	5.31E-03	6.00	60000	2.33	23291
Other inorganic materials	Metal Hydroxide	Proprietary	1.33E-03	1.50	15000	0.58	5823
Other inorganic materials	Carbon Black	1333-86-4	2.66E-04	0.30	3000	0.12	1165
Subtotal			8.85 E-02	100.00	1000000	38.82	388177

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.21 E-01	97.5	975000	53.19	531923
Copper & its alloys	Iron	7439-89-6	2.92 E-03	2.35	23500	1.28	12821
Copper & its alloys	Zinc	7440-66-6	1.49 E-04	0.12	1200	0.07	655
Copper & its alloys	Phosphorus	7723-14-0	3.73 E-05	0.03	300	0.02	164
Subtotal			1.24 E-01	100.00	1000000	54.56	545562

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.24 E-03	100.0	1000000	0.55	5456

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	2.52 E-03	100.0	1000000	1.11	11050

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	9.40 E-04	100.0	1000000	0.41	4122

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	9.09 E-03	100.0	1000000	3.99	39882

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	9.64 E-04	73.54	735400	0.42	4229
Other organic materials	Epoxy resin A	TS ref# 10013	9.64 E-05	7.35	73500	0.04	423
Others	Anhydride	TS ref# 10181	9.64 E-05	7.35	73500	0.04	423
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	3.86 E-05	2.94	29400	0.02	169
Other organic materials	Epoxy resin B	TS ref# 10237	3.86 E-05	2.94	29400	0.02	169
Others	Epoxy resin modifier	TS ref# 10038	3.86 E-05	2.94	29400	0.02	169
Others	Anhydride	TS ref# 10180	3.86 E-05	2.94	29400	0.02	169
Subtotal			1.31 E-03	100.0	1000000	0.58	5751

	Weight (g)	Percentage (%)	PPM
Package Totals	**2.28 E-01**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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